



Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item(s). Note: if the item(s) is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0 or greater is required to complete this declaration.

IPC Standard		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/committeedetail.asp?Committee=2-18		Form Type *	Declaration Type *
Item Number	Item Name	Mfg Item Number	Mfg Item Name	Mfg Item Version	Manufacturing Site

Supplier Information									
Company Name *		Company Unique ID	Unique ID Authority	Response Date *		Response Document ID			
Contact Name		Title - Contact	Phone - Contact	Email - Contact					
Authorized Representative *		Title - Representative	Phone - Representative *	Email - Representative *		URL for Additional Information			
Requester Item Number	Mfg Item Number	Mfg Item Name	Effective Date	Version	Manufacturing Site	Weight	UOM	Unit Volume	
Alternative Recommendation				Alternative Item Comments					

Manufacturing Information section intentionally omitted.

Save the fields in this form to a file

Import fields from a file into this form

Clear all of the fields on this form

RoHS Material Composition Declaration

Legal Definition Type

RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

RoHS Declaration *

Supplier Acceptance

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requestor) and click on Submit Form to have the form returned to the Requester.

RoHS Exemptions

Exemptions: If the declared item(s) does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and checkboxes will appear below. Check all applicable exemptions.

1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.

2a. Mercury in straight fluorescent lamps for general purposes not exceeding halophosphate 10 mg.

2b. Mercury in straight fluorescent lamps for general purposes not exceeding triphosphate with normal lifetime 5 mg.

2c. Mercury in straight fluorescent lamps for general purposes not exceeding triphosphate with long lifetime 8 mg.

3. Mercury in straight fluorescent lamps for special purposes.

4. Mercury in other lamps not specifically mentioned in this list.

5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.

6a. Lead as an alloying element in steel containing up to 0.35% lead by weight.

6b. Lead as an alloying element in aluminum containing up to 0.4% lead by weight.

6c. Lead as an alloying element in copper containing up to 4% lead by weight.

7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).

7b. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications.

7c. Lead in electronic ceramic parts (e.g. piezoelectronic devices).

8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances and preparations piezoelectronic devices).

9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators.

10. Lead used in compliant pin connector systems.

11. Lead as a coating material for a thermal conduction module c-ring.

12a. Lead in optical and filter glass.

12b. Cadmium in optical and filter glass.

13. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight .

14. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

JIG section intentionally omitted.